

# Thermal Conductivity Calculator for Platelet-Based Composites

## 1. Introduction

This program is a **web-based computational tool** for predicting the **effective thermal conductivity ( $k_{eff}$ )** of polymer composites filled with **anisotropic platelet-shaped fillers**, such as hexagonal boron nitride (hBN), graphene, and related two-dimensional materials.

The calculator integrates the effects of:

- Geometrical characteristics of platelet fillers
- In-plane and through-plane anisotropic thermal conductivities of fillers
- Filler volume fraction
- Filler-matrix interfacial thermal resistance ( $R_i$ )
- Filler-filler contact thermal resistance ( $R_c$ )
- Filler orientation factor ( $\cos^2\theta$ )

It is designed for **rapid evaluation and parametric analysis** of thermal transport behavior in platelet-based composites under multi-parameter coupling conditions.

## 2. Model Description

The implemented model is based on **unit-cell analysis and equivalent thermal resistance network theory**, and distinguishes two filler loading regimes:

- **Low filler loading regime:**  $V_f \leq \frac{d}{2a}$
- **High filler loading regime:**  $V_f > \frac{d}{2a}$

Where  $a$  is the radius of platelet filler,  $d$  is the thickness of platelet filler.

The model independently calculates:

- **Through-plane effective thermal conductivity  $k_{\perp}$**
- **In-plane effective thermal conductivity  $k_{\parallel}$**

The overall effective thermal conductivity is obtained by orientation-weighted averaging:

$$k_{eff} = k_{\perp} \cos^2\theta + k_{\parallel} \sin^2\theta$$

## 3. Input Parameters

### 3.1 Filler Geometry

Parameter	Description	Unit
$a$	Radius of platelet filler	m
$d$	Thickness of platelet filler	m

Both **manual input** and **predefined typical dimensions** are supported.

### 3.2 Volume Fraction

Parameter	Description
$V_f$	Filler volume fraction

### 3.3 Thermal Conductivity Parameters

Parameter	Description	Unit
$k_m$	Thermal conductivity of matrix	$\text{W}\cdot\text{m}^{-1}\cdot\text{K}^{-1}$
$k_{f\perp}$	Through-plane thermal conductivity of filler	$\text{W}\cdot\text{m}^{-1}\cdot\text{K}^{-1}$
$k_{f\parallel}$	In-plane thermal conductivity of filler	$\text{W}\cdot\text{m}^{-1}\cdot\text{K}^{-1}$

### 3.4 Interfacial and Contact Thermal Resistance

Parameter	Description	Unit
$R_i$	Filler-matrix interfacial thermal resistance	$\text{m}^2\cdot\text{K}\cdot\text{W}^{-1}$
$R_c$	Filler-filler contact thermal resistance	$\text{m}^2\cdot\text{K}\cdot\text{W}^{-1}$

Note: The interfacial thermal resistance and the filler-filler contact thermal resistance can be obtained either from experimental measurements or directly calculated using theoretical or numerical models.

### 3.5 Orientation Factor

Parameter	Description
$\cos^2\theta$	Orientation factor of platelet fillers

Note:  $\cos^2\theta = 1$ : fully through-plane aligned;  $\cos^2\theta = 0$ : fully in-plane aligned;  $\cos^2\theta \approx 1/3$ : random orientation approximation.

## 4. How to Use

1. Open index.html directly in any modern web browser
  2. Enter or select all required parameters
  3. Click “Calculate the effective thermal conductivity ( $k_{eff}$ )”
  4. The calculated result will be displayed at the bottom of the page as:  $k_{eff}$ : XX.XX W/m·K
- ⚠ No message will appear if any parameter is missing.

## 5. Key Features

- ✓ **No backend required** — runs entirely on HTML + JavaScript;
- ✓ Supports both **continuous input** and **engineering-friendly preset values**;
- ✓ Automatically switches between low- and high-filler-loading regimes;
- ✓ Explicit separation of in-plane and through-plane thermal contributions;
- ✓ Independent control of interfacial and contact thermal resistances.

## 6. Notes and Limitations

- The model is applicable to **platelet-dominated heat conduction composites**;
- In the high-filler-loading regime, results are sensitive to  $R_i$  and  $R_c$
- Input parameters should satisfy geometric and physical constraints
- The results are intended for **theoretical analysis and trend comparison**, not as direct substitutes for experimental measurements

## **7. Typical Applications**

- Design of high-thermal-conductivity polymer composites;
- Optimization of platelet filler size and orientation;
- Analysis of interfacial engineering effects on thermal transport;
- Model-experiment comparison and validation.